

Ji Li

List of Publications by Year in descending order

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docs citations

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403
citing authors

#	ARTICLE	IF	CITATIONS
1	Directly air-cooled compact looped heat pipe module for high power servers with extremely low power usage effectiveness. Applied Energy, 2022, 319, 119279.	10.1	18
2	Characteristics of thermal storage heat pipe charged with graphene nanoplatelets enhanced organic phase change material. Energy Conversion and Management, 2022, 267, 115902.	9.2	24
3	A new cooling strategy for edge computing servers using compact looped heat pipe. Applied Thermal Engineering, 2021, 187, 116599.	6.0	53
4	Transient thermodynamic response and boiling heat transfer limit of dielectric liquids in a two-phase closed direct immersion cooling system. Thermal Science and Engineering Progress, 2021, 25, 100986.	2.7	9
5	Mechanism of a microscale flat plate heat pipe with extremely high nominal thermal conductivity for cooling high-end smartphone chips. Energy Conversion and Management, 2019, 201, 112202.	9.2	67
6	Power-saving exploration for high-end ultra-slim laptop computers with miniature loop heat pipe cooling module. Applied Energy, 2019, 239, 859-875.	10.1	84
7	A robust pulsating heat pipe cooler for integrated high power LED chips. Heat and Mass Transfer, 2017, 53, 3305-3313.	2.1	32
8	Comparative Study on Thermal Performance of Ultrathin Miniature Loop Heat Pipes With Different Internal Wicks. Journal of Heat Transfer, 2017, 139, .	2.1	9
9	An ultra-thin miniature loop heat pipe cooler for mobile electronics. Applied Thermal Engineering, 2016, 109, 514-523.	6.0	83
10	A thermosyphon heat pipe cooler for high power LEDs cooling. Heat and Mass Transfer, 2016, 52, 1541-1548.	2.1	27
11	Comparative studies of pool boiling heat transfer with nano-fluids on porous surface. Heat and Mass Transfer, 2015, 51, 1769-1777.	2.1	15
12	3D Heat Transfer Analysis of a Miniature Copper-Water Vapor Chamber with Wicked Pillars Array. ISRN Mechanical Engineering, 2013, 2013, 1-10.	0.9	6
13	A Compact Loop Heat Pipe With Flat Square Evaporator for High Power Chip Cooling. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2011, 1, 519-527.	2.5	34
14	3D heat transfer analysis in a loop heat pipe evaporator with a fully saturated wick. International Journal of Heat and Mass Transfer, 2011, 54, 564-574.	4.8	63
15	Experimental studies on a high performance compact loop heat pipe with a square flat evaporator. Applied Thermal Engineering, 2010, 30, 741-752.	6.0	125
16	High Power Electronic Component: Review. Recent Patents on Engineering, 2008, 2, 174-188.	0.4	37
17	Geometric optimization of a micro heat sink with liquid flow. IEEE Transactions on Components and Packaging Technologies, 2006, 29, 145-154.	1.3	112
18	Pumping power and heating area dependence of thermal resistance for a large-scale microchannel heat sink under extremely high heat flux. Heat and Mass Transfer, 0, , 1.	2.1	9